

# MA2J116 (MA116)

## Silicon epitaxial planar type

For general purpose

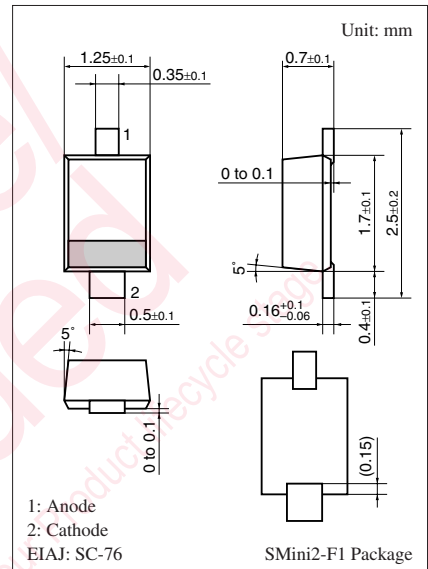
### ■ Features

- Allowing high-density mounting
- Soft recovery characteristic:  $t_{rr} = 100$  ns

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	40	V
Maximum peak reverse voltage	$V_{RM}$	40	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	$I_{FM}$	225	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	500	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $t = 1$  s



Marking Symbol: 1H

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

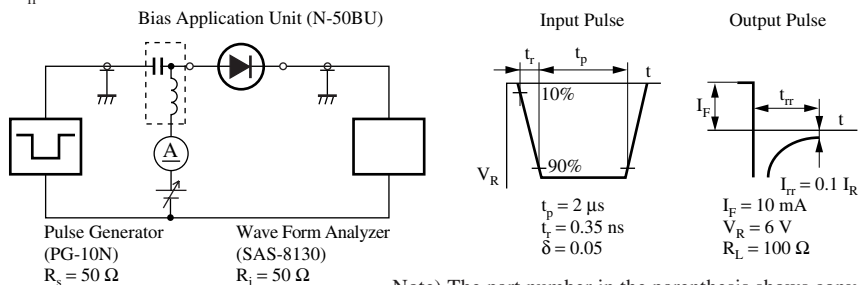
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100$ mA			1.2	V
Reverse voltage	$V_R$	$I_R = 100$ $\mu\text{A}$	35			V
Reverse current	$I_{R1}$	$V_R = 15$ V			5	nA
	$I_{R2}$	$V_R = 40$ V			10	
	$I_{R3}$	$V_R = 35$ V, $T_a = 100^\circ\text{C}$			100	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 6$ V, $f = 1$ MHz		1.0	2.0	pF
Forward dynamic resistance *1	$r_f$	$I_F = 3$ mA, $f = 30$ MHz			3.6	$\Omega$
Reverse recovery time *2	$t_{rr}$	$I_F = 10$ mA, $V_R = 6$ V $I_{rr} = 0.1 I_R$ , $R_L = 100 \Omega$			100	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

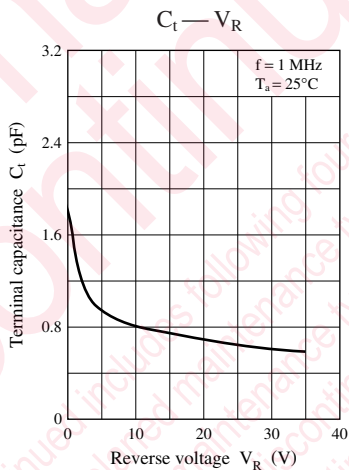
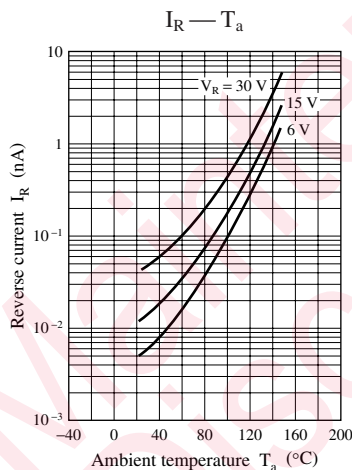
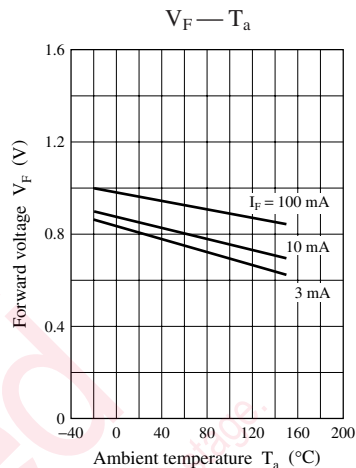
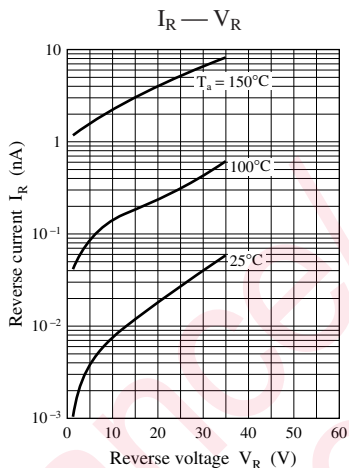
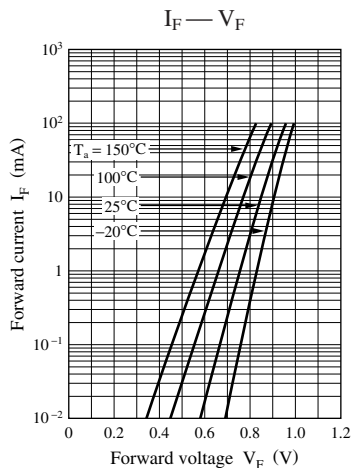
2. Absolute frequency of input and output is 10 MHz.

3. \*1: YHP 4191A RF IMPEDANCE ANALYZER

\*2:  $t_{rr}$  measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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